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Sub. Spec.  
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## POLISHING AND CLEANING COMPOUND DEVICE

### BACKGROUND OF THE INVENTION

This invention relates to a polishing and cleaning compound device  
5 which polishes and cleans both surfaces of a thin disc-shaped work piece  
in series such as a substrate for magnetic discs, a wafer, a glass substrate  
for a liquid-crystal display and a glass substrate for photomask.

JP 2002-254301 A discloses a polishing device which holds careers  
having a plurality of holes for holding a plurality of work pieces between  
10 upper and lower press pratens and makes them revolve and rotate on its  
own axis in normal and inverse directions alternatively to polish both sides  
of a plurality of work pieces.

JP 2001-144057 A discloses that, for example, a process for  
polishing surfaces of wafers is constituted of a plurality of polishing  
15 processes such as a rough polishing process, a precise polishing process,  
and a finish process, whose problem is to well remove slurry which is  
clung on wafers when the wafers are moved between the polishing stations.  
Accordingly, the patent reference discloses that the wafers are washed in a  
condition held on holding heads and washed in a condition installed on a  
20 holding base, and further, that the holding heads are washed  
independently.

Currently, there is a demand to polish a large number of thin  
disc-shaped work pieces such as wafers, and up to now, as disclosed in JP  
2002-254301 A, a plurality of work pieces are polished once by making a  
25 plurality of careers each of which can receive a plurality of work pieces  
and revolve and rotate on its axis between the upper and the lower press